

CLAIMS

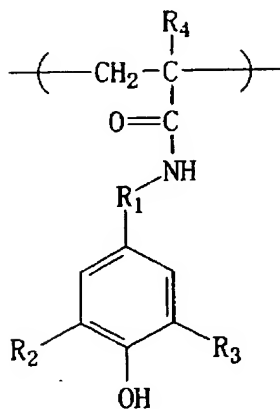
1. A two-layer laminated film for forming bumps,
comprising:

5 (I) a lower layer comprising a composition including a
polymer (A) and an organic solvent (B); and

(II) an upper layer comprising a negative
radiation-sensitive resin composition;

the polymer (A) including a structural unit represented
10 by Formula (1):

[Chem. 1]



. . . . (1)

wherein R_1 is $-(\text{CH}_2)_n-$ where n is an integer of 0 to 3,
and R_2 , R_3 and R_4 are the same or different from one another
15 and are each a hydrogen atom or an alkyl group of 1 to 4 carbon
atoms.

2. The two-layer laminated film for forming bumps according to claim 1, wherein the negative radiation-sensitive resin composition for the upper layer (II) includes a polymer having a carboxyl group and/or a phenolic hydroxyl group (C),
5 a crosslinking agent (D), a radiation-activated radical polymerization initiator (E), and an organic solvent (F).

3. The two-layer laminated film for forming bumps according to claim 2, wherein the polymer (C) has a glass
10 transition temperature (T_g) of not less than 40°C.

4. A transfer film comprising the laminated film claimed in claim 1 and a support film on which the laminated film is provided.

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5. A process for forming bumps on electrode pads on a wiring board, comprising at least:

(a) a step of providing the two-layer laminated film claimed in claim 1 on a substrate and forming a pattern of
20 apertures at positions corresponding to electrode pads;

(b) a step of introducing a low-melting metal in the apertures;

(c) a step of reflowing the low-melting metal by heating to form bumps; and

(d) a step of peeling and removing the two-layer laminated film from the substrate.

6. A process for forming bumps on electrode pads on
5 a wiring board, comprising at least:

(a) a step of providing the two-layer laminated film claimed in claim 1 on a substrate and forming a pattern of apertures at positions corresponding to electrode pads;

(b) a step of introducing a low-melting metal in the
10 apertures;

(d') a step of peeling and removing the two-layer laminated film from the substrate; and

(c') a step of reflowing the low-melting metal by heating to form bumps.

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